

**Method for producing encapsulated chips****Abstract**

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A method for producing encapsulated chips includes preparing a wafer with contacts projecting from a surface of the wafer. The wafer is disposed on a dicing substrate and diced into a plurality of spaced chips on the dicing  
10 substrate. The contacts are covered with a protection arrangement, then injection molding being conducted to introduce encapsulation material into the contacts and the trenches. Then the protection arrangement is removed so that the contacts are exposed.